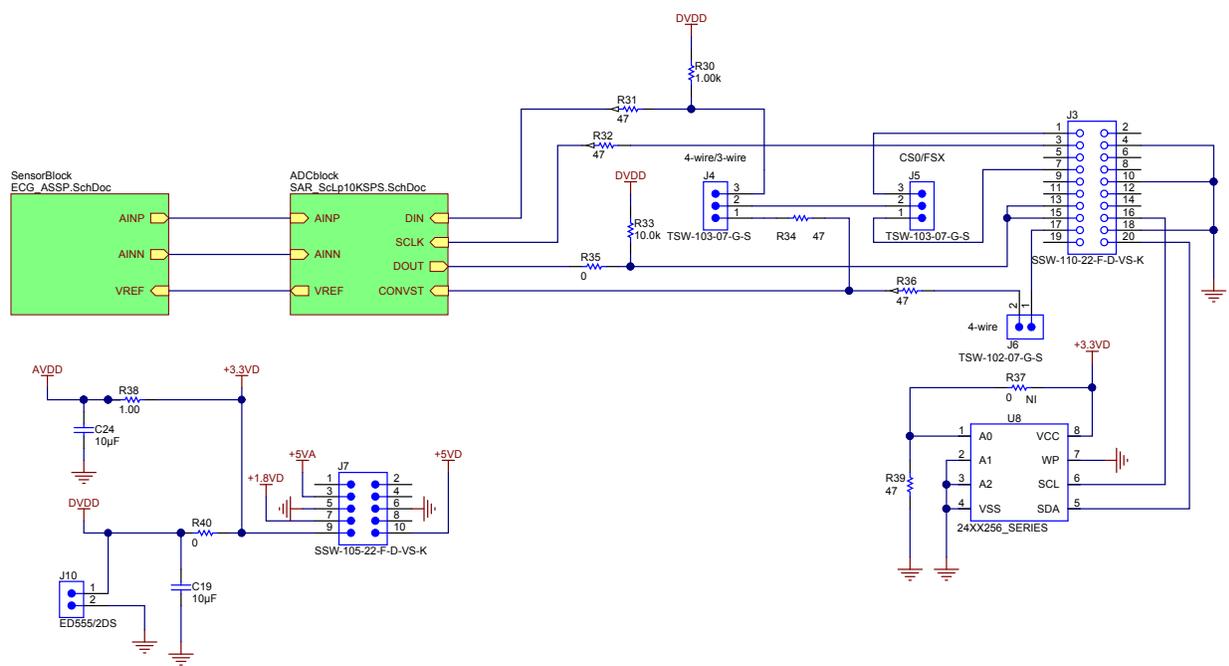


Ultra Low Power, High Precision ECG System

| Revision History | |
|------------------|--------------------------------------|
| Date | Notes |
| A 05/13/2013 | Initial Release |
| B 05/30/2013 | Minor value changes, improved layout |



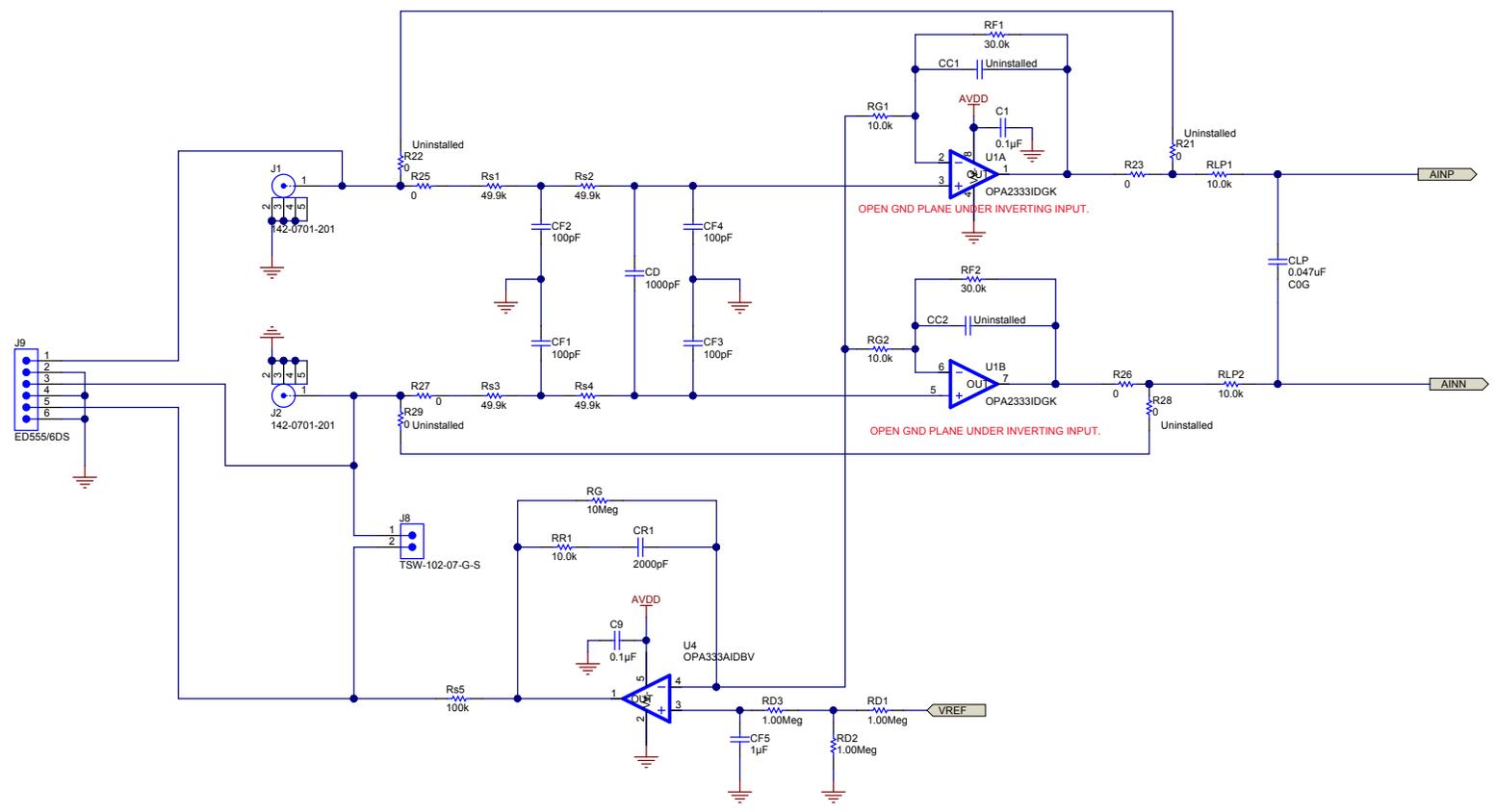
PCB LOGO
Texas Instruments



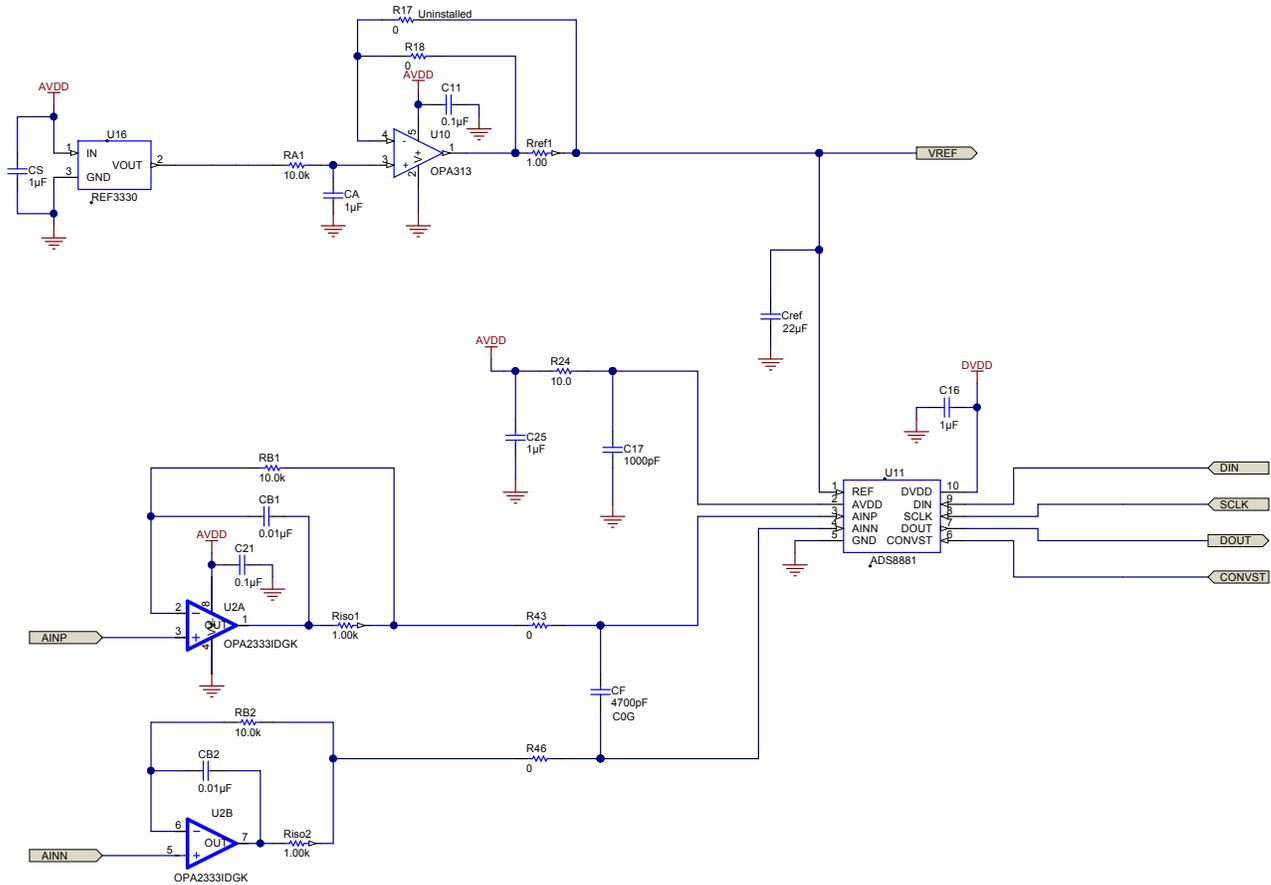
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| | | | | | |
|-----------------------|---------------------|--|----------|------------|---|
| DRAFTSMAN: Dwlrby | DATE: 05/30/2013 | © Texas Instruments 2013 http://www.ti.com | | | |
| DESIGNER: Engineer | DATE: 05/30/2013 | | | | |
| CHECKER: Checker | DATE: 05/30/2013 | TITLE: SCHEMATIC, EVM, TI DESIGNS FOR LOW POWER ECG SYSTEM | | | |
| ENGINEER: Engineer | DATE: 05/30/2013 | | | | |
| APPROVED: Approver | DATE: 05/30/2013 | | | | |
| RELEASED: B McKay | DATE: 05/30/2013 | | | | |
| SCALE N | B SIZE | 6571549 | B REV | 1 SHEET | 3 |

Ultra Low Power, Low Noise, High Zin Gain Block with Shield Drive



Ultra Low Power, 18 Bit, 10 KSPS SAR ADC Block



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